INTEGRATED CIRCUITS

DATA SHEET



74F32Quad 2-input OR gate

Product specification

1990 Oct 04

IC15 Data Handbook





Quad 2-input OR gate

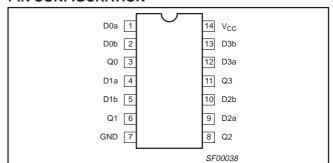
74F32

FEATURE

• Industrial temperature range available (-40°C to +85°C)

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F32	4.1ns	8.2mA

PIN CONFIGURATION



ORDERING INFORMATION

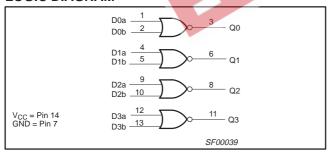
	O	RDER CODE	
DESCRIPTION	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$, $T_{amb} = 0^{\circ}C$ to +70°C	INDUSTRIAL RANGE V_{CC} = 5V ±10%, T_{amb} = -40°C to +85°C	PKG DWG #
14-pin plastic DIP	N74F32N	174F32N	SOT27-1
14-pin plastic SO	N74F32D	174F32D	SOT108-1

INPUT AND OUTPUT LOADING AND FAN OUT TABLE

PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
Dna, Dnb	Data inputs	1.0/1.0	20μA/0.6mA
Qn	Data output	50/33	1.0mA/20mA

NOTE: One (1.0) FAST unit load is defined as: 20µA in the high state and 0.6mA in the low state.

LOGIC DIAGRAM



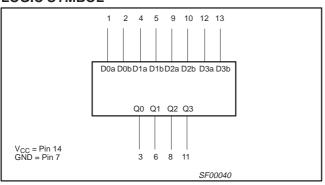
FUNCTION TABLE

INP	UTS	OUTPUT
Dna	Dnb	Qn
L	L	L
L	Н	Н
Н	L	Н
Н	Н	Н

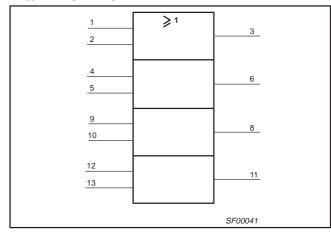
NOTES:

- 1 H = High voltage level
- 2 L = Low voltage level

LOGIC SYMBOL



IEC/IEEE SYMBOL



Quad 2-input OR gate

74F32

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT
V _{CC}	Supply voltage		-0.5 to +7.0	V
V _{IN}	Input voltage		-0.5 to +7.0	V
I _{IN}	Input current		-30 to +5	mA
V _{OUT}	Voltage applied to output in high output state	–0.5 to V _{CC}	V	
I _{OUT}	Current applied to output in low output state		40	mA
_	Operating free cir temperature range	0 to +70	°C	
T _{amb}	Operating free air temperature range	-40 to +85	°C	
T _{stg}	Storage temperature range	-65 to +150	°C	

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER			AN	LIMITS		UNIT
			-05-	MIN	NOM	MAX	
V _{CC}	Supply voltage		27	4.5	5.0	5.5	V
V _{IH}	High-level input voltage		132	2 .0			V
V _{IL}	Low-level input voltage		C			0.8	V
I _{lk}	Input clamp current					-18	mA
I _{OH}	High-level output current					-1	mA
I _{OL}	Low-level output current					20	mA
_	Operating free cir town early up to page	Com	mercial range	0		+70	°C
T _{amb}	Operating free air temperature range	Ind	ustrial range	-40		+85	°C

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TEST CONDITION	DNS ¹		LIMITS	•	UNIT
				1	MIN	TYP ²	MAX	1
V _{OH}	High-level output voltage		$V_{CC} = MIN, V_{IL} = MAX$	±10%V _{CC}	2.5			V
			$V_{IH} = MIN, I_{OH} = MAX$	2.7	3.4		V	
V _{OL}	Low-level output voltage		$V_{CC} = MIN, V_{IL} = MAX$	±10%V _{CC}		0.30	0.50	V
			$V_{IH} = MIN, I_{OI} = MAX$		0.30	0.50	V	
V _{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$		-0.73	-1.2	V	
l _l	Input current at maximum in voltage	put	$V_{CC} = MAX, V_I = 7.0V$				100	μΑ
I _{IH}	High-level input current		$V_{CC} = MAX, V_I = 2.7V$				20	μΑ
I _{IL}	Low-level input current		$V_{CC} = MAX, V_I = 0.5V$				-0.6	mA
Ios	Short-circuit output current ³		V _{CC} = MAX		-60		-150	mA
I _{CC}	Supply current (total)	I _{CCH}	V _{CC} = MAX	$V_{IN} = 4.5V$		6.1	9.2	mA
	I _{CCL}		$V_{CC} = MAX$	V _{IN} = GND		10.3	15.5	mA

- For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

October 4, 1990

All typical values are at $V_{CC} = 5V$, $T_{amb} = 25^{\circ}C$. Not more than one output should be shorted at a time. For testing I_{OS} , the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

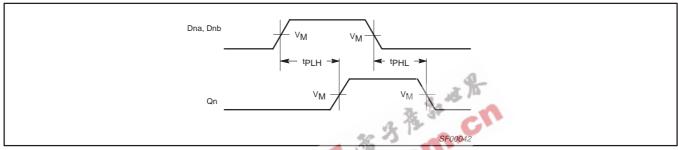
Quad 2-input OR gate

74F32

AC ELECTRICAL CHARACTERISTICS

						LIM	ITS			
SYMBOL	PARAMETER	TEST CONDITION	Tai	_{CC} = +5.0 _{mb} = +25 0pF, R _L =	°C	۵	0V ± 10% C to +70°C R _L = 500Ω	$V_{CC} = +5.$ $T_{amb} = -40^{\circ}$ $C_{L} = 50 pF$	UNIT	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	Propagation delay Dna, Dnb to Qn	Waveform 1	3.0 3.0	4.2 4.0	5.6 5.3	3.0 3.0	6.6 6.3	3.0 3.0	6.6 6.3	ns

AC WAVEFORMS

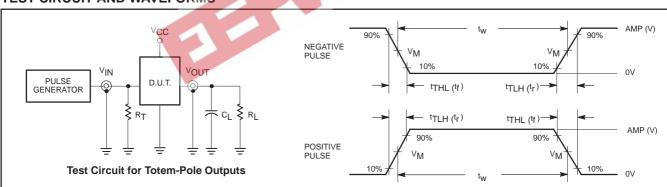


Waveform 1. Propagation delay for inverting outputs

NOTE:

For all waveforms, $V_M = 1.5V$.

TEST CIRCUIT AND WAVEFORMS



DEFINITIONS:

R_L = Load resistor; see AC ELECTRICAL CHARACTERISTICS for value.

C_L = Load capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.

 R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

Input Pulse Definition

family	INP	INPUT PULSE REQUIREMENTS										
lailily	amplitude	V _M	rep. rate	t _w	t _{TLH}	t _{THL}						
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns						

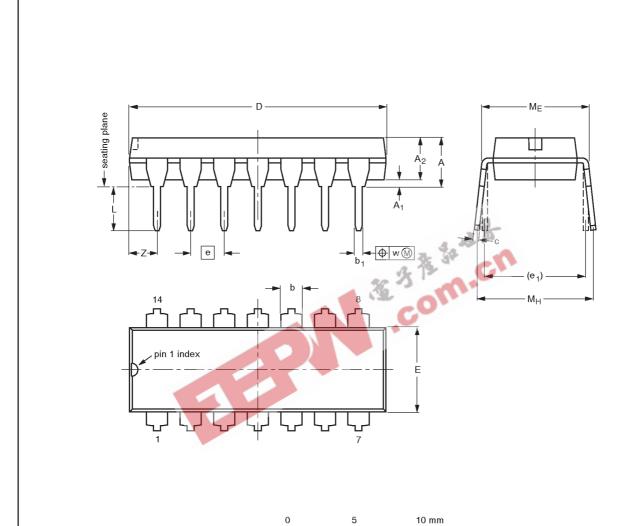
SF00006

Quad 2-input OR gate

74F32

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



scale

DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	1930E DATE	
SOT27-1	050G04	MO-001AA			92-11-17 95-03-11	

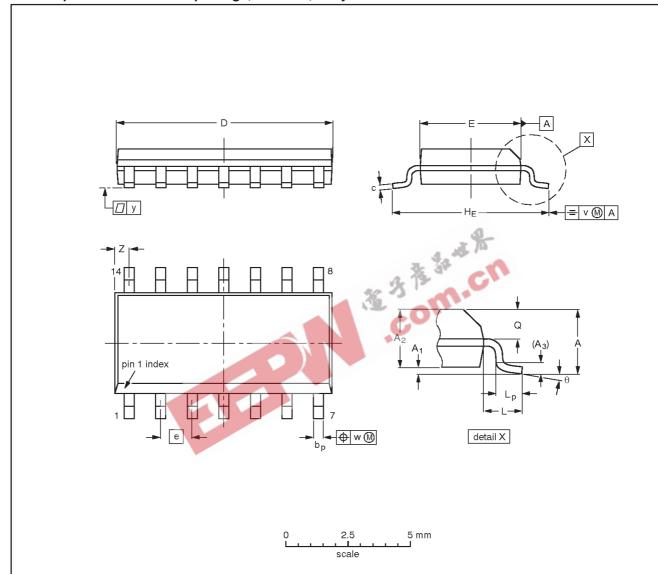
1990 Oct 04 5

Quad 2-input OR gate

74F32

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	А3	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075	0.35 0.34	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT108-1	076E06S	MS-012AB				95-01-23 97-05-22

1990 Oct 04 6

Quad 2-input OR gate

74F32

NOTES



1990 Oct 04 7

Quad 2-input OR gate

74F32

Data sheet status

Data sheet status	Product status	Definition [1]	
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.	
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.	
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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